

AMENDMENTS TO THE CLAIMS

Please amend Claims as follows. Insertions are shown underlined while deletions are ~~struck through~~.

1 -24 (canceled)

25 (currently amended): A method of manufacturing a polishing pad used for chemical mechanical polishing ~~according to Claim 1~~ comprising a polishing region, and a light-transmitting region, said method comprising:

~~measuring light transmittance of a light transmitting material,~~

~~dipping the material in an H₂O₂ aqueous solution at pH 4 for 24 hours,~~

~~measuring light transmittance of said material after dipping,~~

selecting ~~the~~ a light transmittance material as the material having a ΔT of 10 or less which is defined by the equation

$$\Delta T = T_0 - T_1$$

wherein T_1 is a light transmittance of the material for the light-transmitting region in percentage as measured at a plurality of wavelengths between 400 and 700 nm after dipping the material in an H₂O₂ aqueous solution at pH 4 for 24 hours and T_0 is a light-transmittance of the material in percentage as measured at the plurality of the wavelengths before the dipping, and the light-transmitting region is in single layer structure comprising a polyurethane resin comprising 4,4'-diphenylmethane diisocyanate as an organic isocyanate and at least one high-molecular-weight polyol selected from the group consisting of polycaprolactone polyol, polyester polycarbonate polyol, and polyester polyol formed from adipic acid, hexane diol, and ethylene glycol, and

inserting the selecting material to the light transmitting region on the polishing pad.

26. (currently amended): A The method of manufacturing a polishing pad according to Claim 25,

wherein the selecting process further comprising selecting the light transmittance material having the change rate in the light transmittance of the light-transmitting region in wavelength measurements of 400 to 700 nm before dipping is 50 (%) or less,

wherein the change rate (%) = {(maximum light transmittance in 400 to 700 nm – minimum light transmittance in 400 to 700 nm)/maximum light transmittance in 400 to 700 nm}×100.

27. (new): The method of manufacturing a polishing pad according to Claim 25, further comprising providing non foam material for the light transmitting region.

28. (new): The method of manufacturing a polishing pad according to Claim 25, further comprising providing fine-cell foam for the polishing region.

29. (new): The method of manufacturing a polishing pad according to Claim 25, further comprising providing grooves on the polishing side of the polishing region.

30. (new): The method of manufacturing a polishing pad according to Claim 25, further comprising determining ΔT by a method comprising:

measuring light transmittance of the light transmitting material,
dipping the material in an H_2O_2 aqueous solution at pH 4 for 24 hours, and
measuring light transmittance of said material after dipping.

31 (new): A method of manufacturing a polishing pad used for chemical mechanical polishing comprising a polishing region, and a light-transmitting region, said method comprising:

selecting a light transmittance material as material having a ΔT of 10 or less which is defined by the equation

$$\Delta T = T_0 - T_1$$

wherein T_1 is a light transmittance of the material for the light-transmitting region in percentage as measured at a plurality of wavelengths between 400 and 700 nm after dipping the material in an KOH aqueous solution at pH 11 for 24 hours and T_0 is a light-transmittance of the material in percentage as measured at the plurality of the wavelengths before the dipping, and the light-transmitting region is in single layer structure comprising a polyurethane resin comprising 4,4'-diphenylmethane diisocyanate as an organic isocyanate and at least one high-molecular-weight polyol selected from the group consisting of polycaprolactone polyol, polyester polycarbonate polyol, and polyester polyol formed from adipic acid, hexane diol, and ethylene glycol, and

inserting the selecting material to the light transmitting region on the polishing pad.

32. (new): The method of manufacturing a polishing pad according to Claim 31, wherein the selecting process further comprising selecting the light transmittance material having the change rate in the light transmittance of the light-transmitting region in wavelength measurements of 400 to 700 nm before dipping is 50 (%) or less,

wherein the change rate (%) = {(maximum light transmittance in 400 to 700 nm – minimum light transmittance in 400 to 700 nm)/maximum light transmittance in 400 to 700 nm}×100.

33. (new): The method of manufacturing a polishing pad according to Claim 31, further comprising providing non foam material for the light transmitting region.

34. (new): The method of manufacturing a polishing pad according to Claim 31, further comprising providing fine-cell foam for the polishing region.

35. (new): The method of manufacturing a polishing pad according to Claim 31, further comprising providing grooves on the polishing side of the polishing region.

36. (new): The method of manufacturing a polishing pad according to Claim 31, further comprising determining ΔT by a method comprising:

measuring light transmittance of the light transmitting material,
dipping the material in an KOH aqueous solution at pH 11 for 24 hours, and
measuring light transmittance of said material after dipping.